

N-Channel Enhancement Mode Power MOSFET

Description

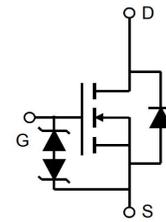
The G250N03IE uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

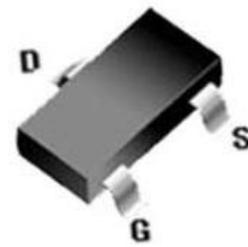
- V_{DS} 30V
- I_D (at $V_{GS} = 10V$) 5.3A
- $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 25m Ω
- $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 30m Ω
- $R_{DS(ON)}$ (at $V_{GS} = 2.5V$) < 50m Ω
- 100% Avalanche Tested
- RoHS Compliant
- ESD (HBM): 3.5KV

Application

- Power switch
- DC/DC converters



Schematic diagram



SOT-23

Ordering Information

Device	Package	Marking	Packaging
G250N03IE	SOT-23	G250N03	3000pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Continuous Drain Current	I_D	5.3	A
Pulsed Drain Current (note1)	I_{DM}	22	A
Gate-Source Voltage	V_{GS}	± 10	V
Power Dissipation	P_D	1.4	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ\text{C}$

Thermal Resistance

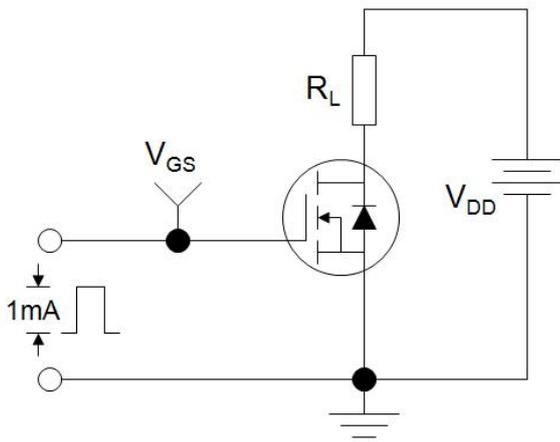
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	89	$^\circ\text{C/W}$

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 10V$	--	--	± 10	μA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	1	1.3	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 4A$	--	21	25	m Ω
		$V_{GS} = 4.5V, I_D = 4A$	--	24	30	
		$V_{GS} = 2.5V, I_D = 2A$	--	37	50	
Forward Transconductance	g_{FS}	$V_{GS} = 5V, I_D = 4A$	--	10	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 15V,$ $f = 1.0MHz$	--	573	--	pF
Output Capacitance	C_{oss}		--	66	--	
Reverse Transfer Capacitance	C_{rss}		--	56	--	
Total Gate Charge	Q_g	$V_{DD} = 15V,$ $I_D = 4A,$ $V_{GS} = 4.5V$	--	9.1	--	nC
Gate-Source Charge	Q_{gs}		--	2.1	--	
Gate-Drain Charge	Q_{gd}		--	2.8	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V,$ $I_D = 4A,$ $R_G = 3\Omega$	--	3	--	ns
Turn-on Rise Time	t_r		--	2.8	--	
Turn-off Delay Time	$t_{d(off)}$		--	25	--	
Turn-off Fall Time	t_f		--	4	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	5.3	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 4A, V_{GS} = 0V$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 4A, V_{GS} = 0V$ $di/dt = 100A/\mu s$	--	2	--	nC
Reverse Recovery Time	T_{rr}		--	6	--	ns

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G

Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

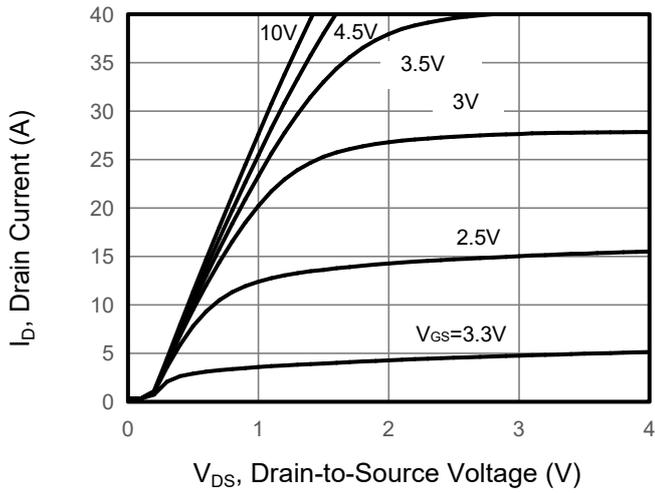


Figure 2. Transfer Characteristics

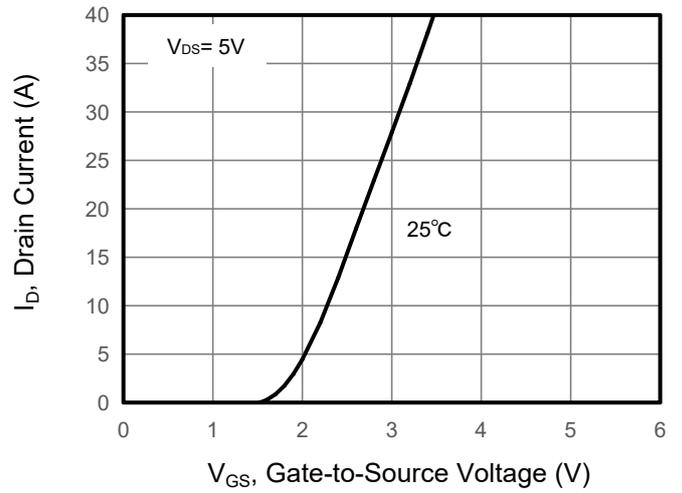


Figure 3. Drain Source On Resistance

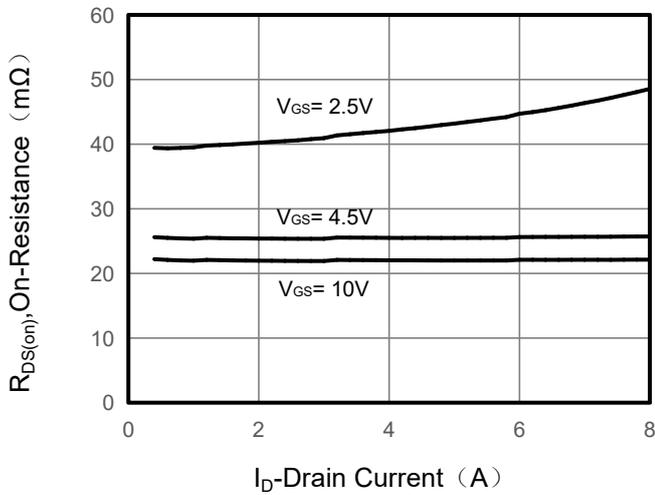


Figure 4. Gate Charge

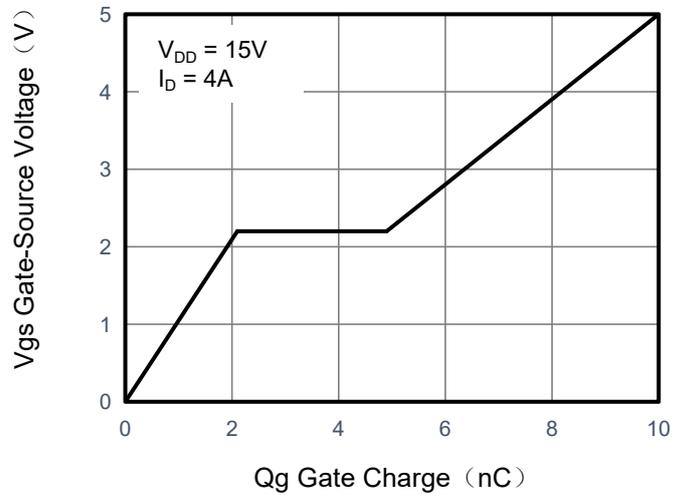


Figure 5. Capacitance

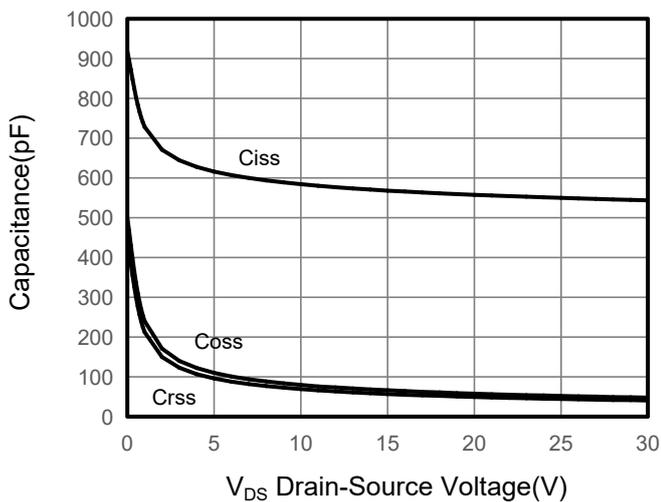
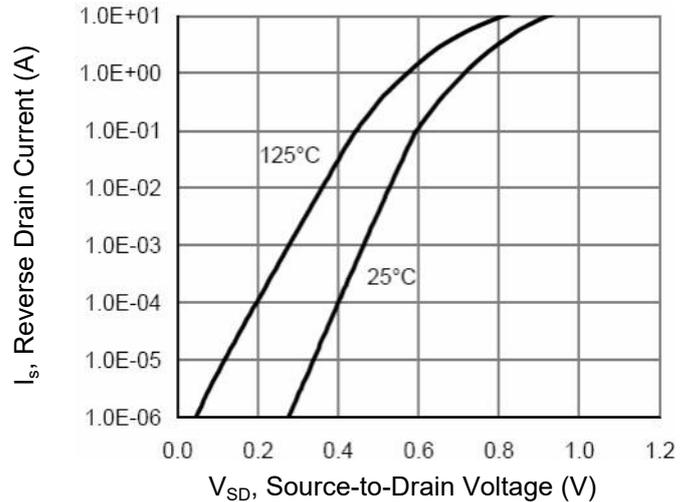


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

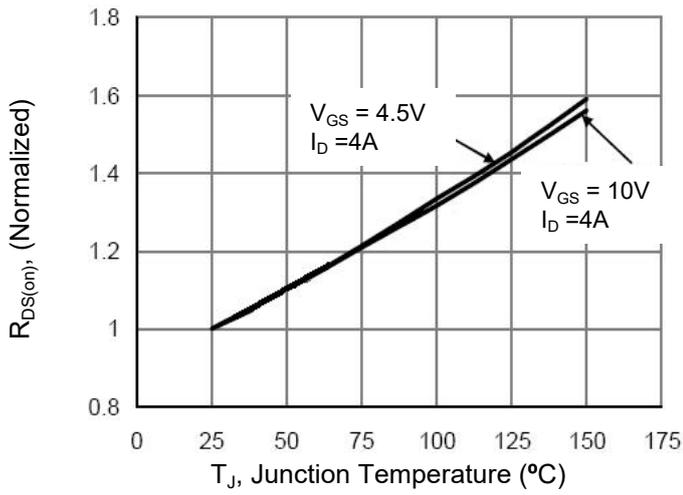


Figure 8. Safe Operation Area

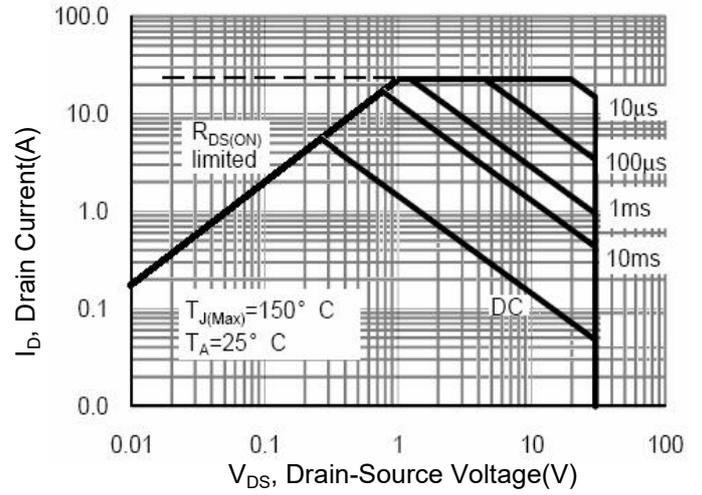
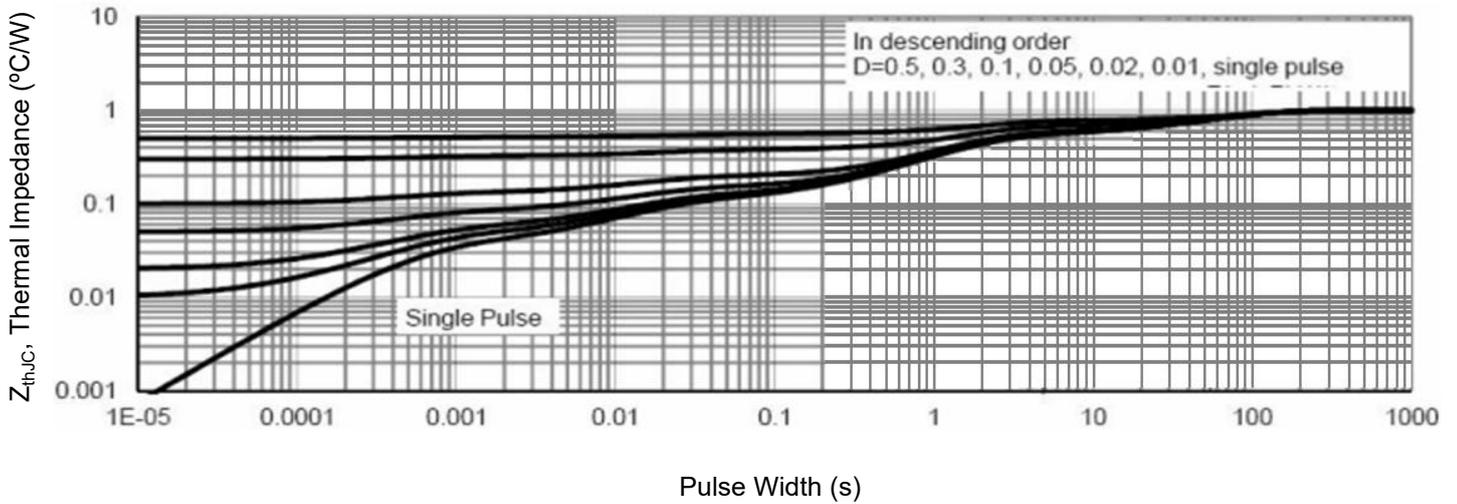
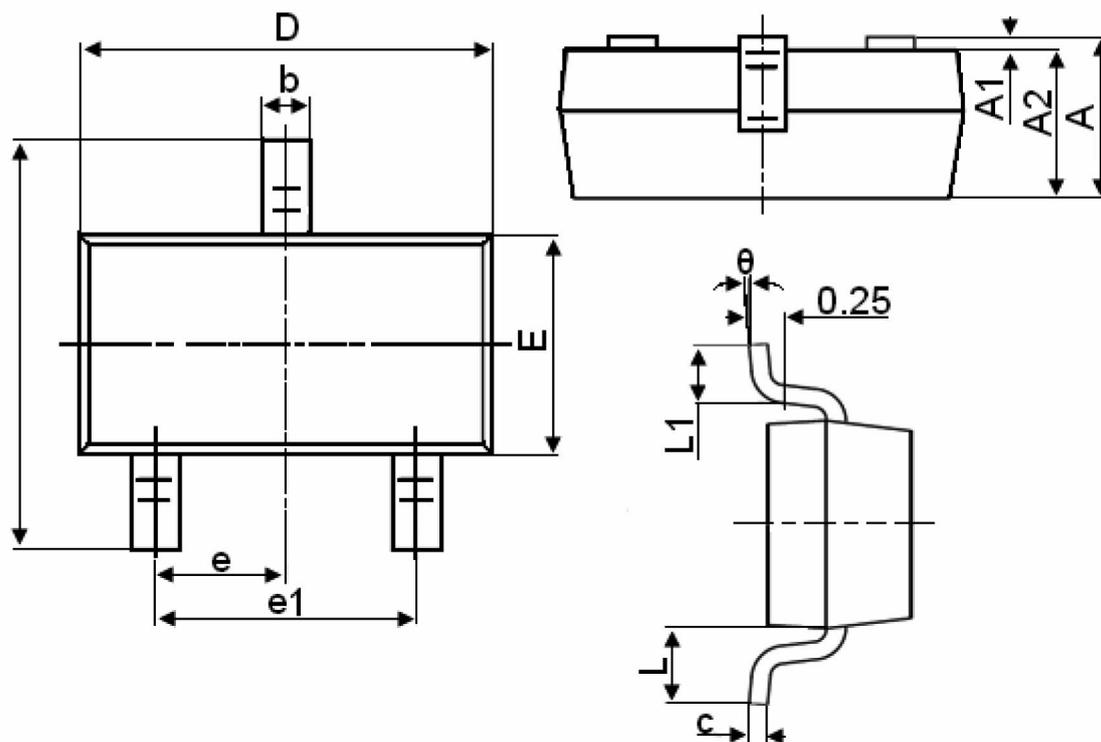


Figure 9. Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°